

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 2 | "6822316".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 17:57 |
| L2 | 33 | ("3636619" "3962052" "4348253" "4416054" "4419182" "4808273" "4930216" "4954875" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5426072" "5532612" "5548091" "5578526" "5599744" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6168969" "6400172").PN. OR ("6822316"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L3 | 82 | bare with wafer with via | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L4 | 15 | ("3761782" "3947840" "4499655" "5229647" "5378927" "5406125" "5455445" "5510655" "5528080" "5552338" "5552633" "5608264" "5623160" "5675180" "5682062").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L5 | 1 | "5973,396".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L6 | 1 | "5973396".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L7 | 52 | ("3761782" "3947840" "4499655" "4764846" "4972248" "4983533" "5128831" "5229647" "5266833" "5298767" "5378927" "5386142" "5406125" "5434745" "5455445" "5468997" "5481133" "5481134" "5510655" "5528080" "5552633" "5608264" "5623160" "5675180" "5682062").PN. OR ("5973396"). URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L9 | 27 | ("5973396").URPN. | USPAT | OR | ON | 2005/11/08 17:57 |
| L10 | 863 | wafer with via with pad | USPAT | OR | ON | 2005/11/08 17:57 |
| L11 | 0 | L10 and pristine adj (substrate wafer) | USPAT | OR | ON | 2005/11/08 18:03 |
| L12 | 28 | pristine adj (substrate wafer) | USPAT | OR | ON | 2005/11/08 17:57 |
| L13 | 822 | unprocessed adj (substrate wafer) | USPAT | OR | ON | 2005/11/08 18:02 |
| L14 | 22 | unprocessed adj (substrate wafer) with via | USPAT | OR | ON | 2005/11/08 17:57 |

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| L15 | 34 | ("20010005046" "3636619" "3962052" "4348253" "4416054" "4808273" "4930216" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5532612" "5548091" "5578526" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6030855" "6110825" "6168969" "6198168" "6268660" "6495454").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L16 | 29 | unprocessed near2 (substrate wafer) with via | USPAT | OR | ON | 2005/11/08 18:00 |
| L17 | 7 | L16 not L14 | USPAT | OR | ON | 2005/11/08 17:57 |
| L18 | 49 | unprocessed near2 (substrate wafer) with via | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 18:04 |
| L19 | 20 | L18 not L16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 17:57 |
| L20 | 1 | virgin near2 (substrate wafer) with via | USPAT | OR | ON | 2005/11/08 17:57 |
| L21 | 1197 | (substrate wafer) with un\$2processed | USPAT | OR | ON | 2005/11/08 17:57 |
| L22 | 34 | (substrate wafer) with un\$2processed with via | USPAT | OR | ON | 2005/11/08 17:57 |
| L23 | 5 | L22 not L16 | USPAT | OR | ON | 2005/11/08 17:57 |
| L24 | 57 | (substrate wafer) with un\$2processed with via | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 17:57 |
| L25 | 28 | L24 not L16 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 17:57 |

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| L26 | 33 | ("3636619" "3962052" "4348253" "4416054" "4419182" "4808273" "4930216" "4954875" "4978639" "4984358" "5037782" "5148265" "5148266" "5229647" "5252842" "5258330" "5284796" "5313366" "5424245" "5426072" "5532612" "5548091" "5578526" "5599744" "5661087" "5682062" "5861662" "5898215" "5952712" "5986339" "6005292" "6168969" "6400172").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/11/08 17:57 |
| L27 | 2 | "6822316".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 17:59 |
| L29 | 414 | (257/621).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:02 |
| L30 | 2376 | (257/774).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L31 | 780 | (257/776).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L32 | 1773 | (257/690).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L33 | 256 | (257/699).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L34 | 1686 | (257/700).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |

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| L35 | 330 | (257/708).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L36 | 2628 | (257/778).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:01 |
| L37 | 613 | (257/618).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:02 |
| L38 | 1648 | (257/777).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/11/08 18:02 |
| L39 | 10992 | 29 30 31 32 33 34 35 36 37 38 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 18:02 |
| L40 | 8 | 39 and unprocessed near2 (substrate wafer) | USPAT | OR | ON | 2005/11/08 18:02 |
| L41 | 9 | 39 and unprocessed with (substrate wafer) | USPAT | OR | ON | 2005/11/08 18:03 |
| L42 | 12 | 39 and unprocessed .same(substrate wafer) | USPAT | OR | ON | 2005/11/08 18:03 |
| L43 | 427 | 39 and (pristine virgin new unprocessed) same(substrate wafer) | USPAT | OR | ON | 2005/11/08 18:13 |
| L44 | 224 | 39 and (pristine virgin new unprocessed) with (substrate wafer) | USPAT | OR | ON | 2005/11/08 18:04 |
| L45 | 302 | 39 and (pristine virgin new unprocessed) with (substrate wafer) | US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB | OR | ON | 2005/11/08 18:04 |
| L46 | 138 | 45 and (substrate wafer) with via | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 18:04 |

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| L47 | 199 | <i>45 and (substrate wafer) with (hole via throughhole though cavity)</i> | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/11/08 18:05 |
| L48 | 476 | <i>((pristine virgin new unprocessed) and (substrate wafer)and (hole via throughhole though cavity)).clm.</i> | US-PGPUB | OR | ON | 2005/11/08 18:15 |
| L51 | 101 | <i>((pristine virgin new unprocessed) and (substrate wafer)and (hole via throughhole though cavity) and (pad interconnect\$3 I/O)).clm.</i> | US-PGPUB | OR | ON | 2005/11/08 18:15 |